



## CONTROLLING DIMENSION: INCH

### NOTES: UNLESS OTHERWISE SPECIFIED

- STANDARD LEAD FINISH:  
200 MICROINCHES / 5.08 MICROMETERS MINIMUM  
SOLDER THICKNESS PER SIDE ON COPPER.
- DIMENSION DOES NOT INCLUDE MOLD PROTRUSION.  
MAXIMUM ALLOWABLE MOLD PROTRUSION .010 IN / 0.25mm  
PER SIDE.
- REFERENCE JEDEC REGISTRATION MO-047, VARIATION AA,  
DATED 5/90.

## REVISIONS

LTR	DESCRIPTION	E.C.N.	DATE	BY/APP'D
K	REVISE & REDRAW TO STD FORMAT	09318	09/17/92	DEG/SL
L	ADD COPLANARITY & SEATING PLANE, CONVERT LIMIT DIM'S TO NOM±TOL. DIM 45°X.065[1.65] WAS 45°X.065[1.14]; DIM .390±.005 WAS .385-3.95	10036	12/01/93	MS/SL

APPROVALS	DATE	NATIONAL SEMICONDUCTOR CORPORATION		
DRAWN D. E. GRADY	09/17/92	2900 Semiconductor Drive, Santa Clara, CA 95052-8090		
DFG. CHK. M. J. J. J.	12/03/93	PLASTIC CHIP CARRIER, SQ., .050 LD PITCH, 20 LEAD		
ENGR. CHK. S. J. J. J.	12/01/93			
APPROVAL				
PROJECTION INCH [MM]		SCALE N/A	SIZE B	DRAWING NUMBER MKT-V20A
		DO NOT SCALE DRAWING	SHEET 1 OF 1	REV L